

**Rohm and Haas Electronic Materials
Introduces the Latest Products for Printed Circuit Board Manufacturers at
the 38th JPCA Show 2008**

Tokyo, June 12, 2008 — Rohm and Haas Electronic Materials, a global pioneer in the creation and development of innovative technologies and solutions for the specialty materials industry, will introduce the latest products for printed circuit board manufacturers, such as LithoJet™ inkjet materials for electronic fabrication, and CIRCUPPOSIT™, a high performance electroless copper plating process, at the 38th Japan Printed Circuit Association (JPCA) Show 2008 – Stand #5G-13, Hall East 5, Tokyo Big Sight.

Most of today's electronic devices require sophisticated circuits and electronic components. As demand grows for increasingly advanced materials and manufacturing technologies and processes, the industry requires continued innovation. Especially within the Japanese market, companies are moving into high value added fields and sophisticated technologies, prompting further advancement and high performance in surface finishing applications. In such a market environment, Rohm and Haas's Circuit Board Technologies business unit is focusing on the current and future advanced metallization technologies essential to printed circuit board manufacturing and circuit design. The company offers a broad set of surface finishing applications and related process chemicals, and will introduce a variety of products and technologies at the JPCA Show. Below are some of main products exhibited at the show.

Inkjet materials for electronic fabrication, LithoJet™

LithoJet is an environmentally conscious and high performance material that is an alternative to conventional photolithography materials,, enabling high resolution and superior printing imagery essential in electronic component/device design. By employing LithoJet™, manufacturers can go directly from CAD station to imaging without going through the conventional photolithography process. Moreover, it has a high degree of acid resistance and viscosity, suitable even for conventional etching processes. This allows both high resolution and superior pattern imagery, which is compatible with various types of electronic device and circuit board manufacturing processes.

High performance electroless copper plating process, CIRCUPPOSIT™

Compatible with a semi-additive process (one of the processes suitable for high density wiring design), as well as with fine patterning, high imaging, and high frequency due to high viscosity on low texturized profile surface. Hence, CIRCUPPOSIT enables uniform copper deposits on insulator and inside vias and copper adhesion reliability at the bottom of vias.

Rohm and Haas announced "Vision 2010" as a key business strategy in 2006, based on detailed analyses of business achievement, portfolios, environment, and opportunities focusing on organic growth, and pursuing further growth overall. President of Rohm and Haas Japan, Mr. Watanabe has stated "focusing on our core activities such as strengthening 'R&D', 'our growing market segments', and 'pioneering new markets', our sales objective in Electronic Materials Group is to double the business to 3.5 billion dollars by 2010. By applying our profound experience and knowledge and continuously developing innovative technologies and solutions for our customers, we will strive to develop excellent products and technologies required in electrical wiring and next generation device designing for the future."

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About Rohm and Haas Electronic Materials

Rohm and Haas Electronic Materials develops and delivers innovative material solutions and processes to the electronic and optoelectronic industries. Focused on the circuit board, semiconductor manufacturing, advanced packaging, and flat panel display industries, its products and technologies are integral elements in electronic devices around the world.

About Rohm and Haas's Circuit Board Technologies

Focusing on metallization, imaging and optoelectronics applications, Rohm and Haas's Circuit Board Technologies business develops and delivers these industry-leading processes and products: electroless copper plating; electrolytic copper plating; liquid photoresists; dry film photoresists; stripper/etchant/developers; electroless nickel immersion gold; and adhesion promotion.

About Rohm and Haas Company

Leading the way since 1909, Rohm and Haas (NYSE:ROH) is a global pioneer in the creation and development of innovative technologies and solutions for the specialty materials industry. The company's technologies are found in a wide range of markets including: Building and Construction, Electronics, Food and Retail, Household and Personal Care, Industrial Process, Packaging, Paper, Transportation and Water. Our innovative technologies and solutions help to improve life everyday, around the world. Based in Philadelphia, PA, the company generated annual sales of approximately \$8.2 billion in 2006. Visit www.rohmhaas.com for more information. Imagine the possibilities™.

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